



## Product Change Notification / KSRA-20BGKY389

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### Date:

11-Apr-2023

### Product Category:

8-bit Microcontrollers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4023.001 and 4023.002 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L (7x7x1.0mm) and 48L TQFP (7x7x1.0mm) package using gold (Au) wire.

### Affected CPNs:

[KSRA-20BGKY389\\_Affected\\_CPN\\_04112023.pdf](#)

[KSRA-20BGKY389\\_Affected\\_CPN\\_04112023.csv](#)

### Notification Text:

#### PCN Status:

Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MTAI as a new assembly site for selected Atmel products available in 32L (7x7x1.0mm) and 48L TQFP (7x7x1.0mm) package using gold (Au) wire.

#### Pre Change:

Assembled at ASCL assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, G700 and CEL-9240 molding compound, EN4900G die attach, and C194-ESH lead frame material with MSL Level 3 classification

#### Post Change:

Assembled at MTAI assembly site using gold (Au) bond wire, G700 molding compound, 3280 die attach, and C7025 lead frame material with MSL Level 1 classification

**Pre and Post Change Summary:**

	Pre Change		Post Change
<b>Assembly Site</b>	ASE Group Chung-Li / ASCL		Microchip Technology Thailand (HQ) / MTAI
<b>Wire material</b>	CuPdAu		Au
<b>Die attach material</b>	EN4900G		3280
<b>Molding compound material</b>	G700		CEL-9240
<b>Lead frame material</b>	C194-ESH		C7025
<b>MSL</b>	MSL 3		MSL 1

**Impacts to Data Sheet:**

None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying MTAI as a new assembly site

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**March 14, 2020(date code: 2011)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	December 2019				→	February 2020					March 2020				
	49	50	51	52		05	06	07	08	09	10	11	12	13	14
Workweek				X											
Initial PCN Issue Date				X											
Qual Report Availability								X							
Final PCN Issue Date								X							
Estimated Implementation Date												X			

**Method to Identify Change:** Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**December 23, 2019: Issued initial notification.

February 14, 2020: Issued final notification. Attached the Qualification Report. Updated the pre and post change to add

CEL-9240 molding compound material. Provided estimated first ship date to be on March 14, 2020 **April 11, 2023**: Re-issued final notification. Updated affected parts list to include ATMEGA328PB-ABTVAO catalog part number (CPN).

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_KSRA-20BGKY389\\_Qual\\_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

## Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.